

# RD5CYD08

### **IGBT** Driver

REJ03D0180-0400Z Rev.4.00 Jul. 12, 2004

### **Description**

The RD5CYD08 has two-input AND gate in a 5 pin package. This product is suited as IGBT Driver IC for the strobe.

#### **Features**

- Supplied on emboss taping for high-speed automatic mounting.
- Supply voltage range : 4.0 to 6.0 V Operating temperature range: -40 to +85°C
- High drive current

$$I_{OH}$$
 short = -130 mA (min) (@V<sub>CC</sub> = 5.0 V)

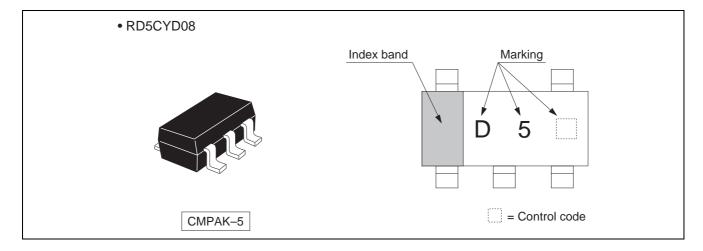
• Low sink current

$$I_{OL}$$
 short = 40 mA (max) (@V<sub>CC</sub> = 5.0 V)

• Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
RD5CYD08CME		CMPAK-5V CMPAK-5V(O)	СМ	E (3,000 pcs/reel)

#### **Outline and Article Indication**

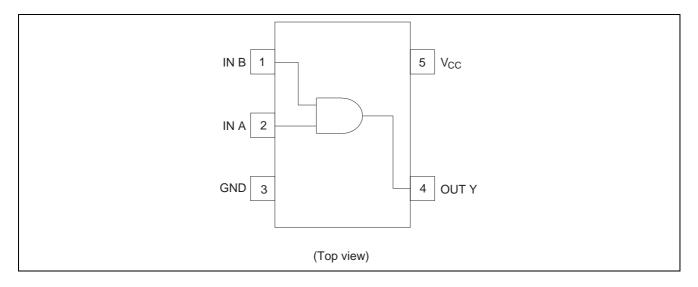


# **Function Table**

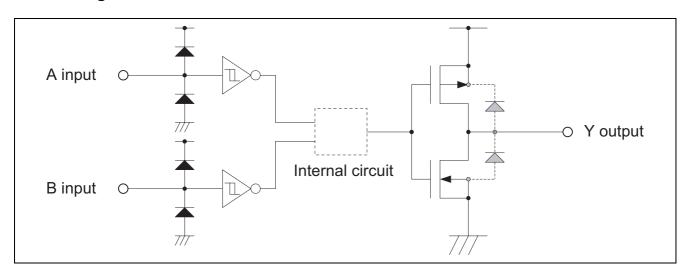
Inp		
Α	В	Output Y
L	L	L
Н	L	L
L	Н	L
Н	Н	Н

H : High level L : Low level

# **Pin Arrangement**



# **Block Diagram**



# **Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit	Test Conditions
Supply voltage range	V <sub>CC</sub>	-0.5 to 7.0	V	
Input voltage range *1	Vi	$-0.5$ to $V_{CC} + 0.5$	V	
Output voltage range *1, 2	Vo	-0.5 to V <sub>CC</sub> + 0.5	V	
Input clamp current	I <sub>IK</sub>	±20	mA	$V_I < 0 \text{ or } V_I > V_{CC}$
Output clamp current	I <sub>OK</sub>	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	Io	-200	mA	V <sub>O</sub> = 0
		100		$V_O = V_{CC}$
Continuous current through V <sub>CC</sub> or GND	I <sub>CC</sub> or I <sub>GND</sub>	±200	mA	
Maximum power dissipation at Ta = 25°C (in still air) *3	P <sub>T</sub>	200	mW	
Storage temperature	Tstg	-65 to 150	°C	

Notes: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore no two of which may be realized at the same time.

- 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed. When Over shoot / Under shoot pulse width is under 10 ns, input and output voltage permit to -1.5 V or V<sub>CC</sub>+1.5 V.
- 2. This value is limited to 5.5 V maximum.
- 3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

### **Recommended Operating Conditions**

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V <sub>CC</sub>	4.0	6.0	V	
Input voltage range	VI	0	Vcc	V	
Output voltage range	Vo	0	V <sub>CC</sub>	V	
Operating free-air temperature	Ta	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

#### **Electrical Characteristic**

Ta = -40 to  $85^{\circ}C$ 

Item	Symbol	V <sub>cc</sub> (V)	Min	Тур	Max	Unit	Test condition
Input voltage	V <sub>IH</sub>	4.0	V <sub>CC</sub> ×0.7	_	_	V	
		4.5 to 5.5	V <sub>CC</sub> ×0.7	_	_		
	V <sub>IL</sub>	4.0	_	_	V <sub>CC</sub> ×0.3		
		4.5 to 5.5	_	_	V <sub>CC</sub> ×0.3		
	V <sub>H</sub>	4.0	_	0.35	_		
		5.0	_	0.40	_		
Output current	I <sub>OH</sub> short	4.0	-65	-85	-105	mA	$V_O = 0 V$
		5.0	-100	-130	-160		
	I <sub>OL</sub> short	4.0	20	28	40		$V_O = V_{CC}$
		5.0	30	40	50		
Input current	I <sub>IN</sub>	5.5	_	_	±5	μΑ	$V_{IN} = 5.5 \text{ V or GND}$
Quiescent	Icc	5.5	_	_	10	μΑ	$V_{IN} = V_{CC}$ or GND,
supply current							I <sub>O</sub> = 0
Input capacitance	C <sub>IN</sub>	5.0	_	2.5		pF	$V_{IN} = V_{CC}$ or GND



# **Switching Characteristics**

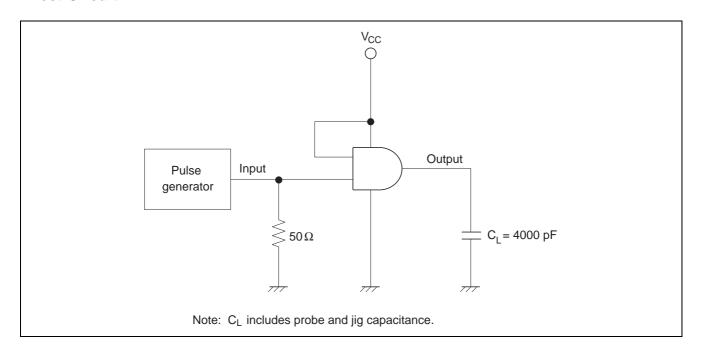
 $V_{CC} = 4.0 \text{ V}$ 

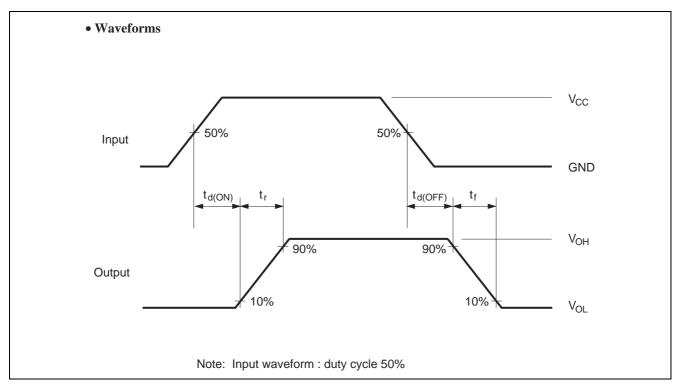
		Ta = -40 to 85°C				Test	FROM	TO
Item	Symbol	Min	Тур	Max	Unit	Conditions	(Input)	(Output)
Propagation delay time	t <sub>d(ON)</sub>	_	_	80	ns	$C_L = 4000 \text{ pF}$	A or B	Υ
	t <sub>d(OFF)</sub>	_	_	160				
Output rise time	t <sub>r</sub>	_	_	1000				
Output fall time	t <sub>f</sub>	_	_	2000				

 $V_{CC}=5.0\pm0.5\ V$ 

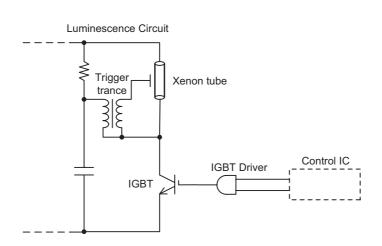
		Ta = -40 to 85°C				Test	FROM	TO
Item	Symbol	Min	Тур	Max	Unit	Conditions	(Input)	(Output)
Propagation delay time	t <sub>d(ON)</sub>	_	_	70	ns	C <sub>L</sub> = 4000 pF	A or B	Υ
	t <sub>d(OFF)</sub>	_	_	140				
Output rise time	t <sub>r</sub>	_	_	800				
Output fall time	t <sub>f</sub>	_	_	1500	1			

### **Test Circuit**





# **Application Note (Strobe circuit)**



### Combination example

SYSTEM	IGBT	IGBT Driver	Control IC
5.0 V	CY25BAJ –8F CY25AAJ –8F	RD5CYD08 RD5CYDT08	5.0 V signal
	CY25AAJ –8F2	CRD5CYD108 ◀	3.3 V signal
3.3 V	CY25BAH-8F ◀	RD3CYD08 ◀	3.3 V signal

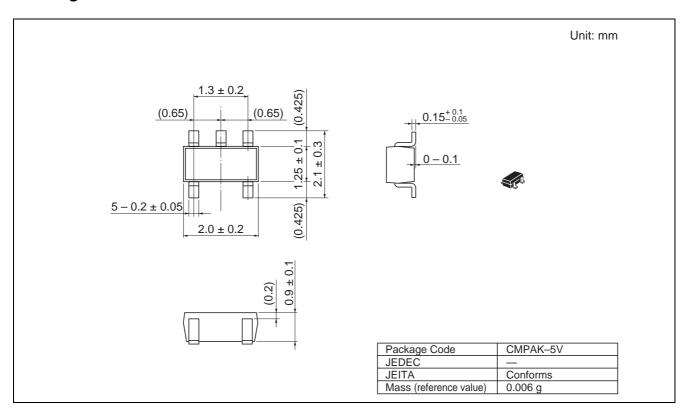
# IGBT Driver Lineup

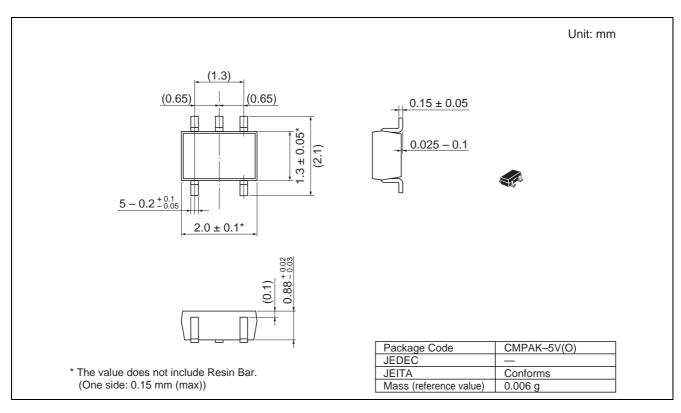
TYPE No.	Specification	Package
RD5CYD08	Vcc = 4.0 to 6.0V CMOS level input I <sub>OH</sub> (short) = -130mA(typ) @ Vcc=5.0V I <sub>OL</sub> (short) = 40mA(typ) @ Vcc=5.0V	
RD5CYDT08	RD5CYDT08 $ \begin{array}{c} \text{Vcc} = 4.0 \text{ to } 6.0 \text{V TTL level input} \\ \text{I}_{\text{OH}}(\text{short}) = -130 \text{mA(typ)} @ \text{Vcc=} 5.0 \text{V} \\ \text{I}_{\text{OL}}(\text{short}) = 40 \text{mA(typ)} @ \text{Vcc=} 5.0 \text{V} \\ \end{array} $	
RD3CYD08	Vcc = 2.0 to 3.6V CMOS level input $I_{OH}(short) = -130mA(typ)$ @ Vcc=3.3V $I_{OL}(short) = 45mA(typ)$ @ Vcc=3.3V	

### **IGBT** Lineup

TYPE No.	Specification	Package
CY25AAJ-8F	$V_{CES} = 400V(max)$ , $I_{CP} = 150A(max)$ , 4V drive	TSSOP-8
CY25BAJ-8F	$V_{CES} = 400V(max)$ , $I_{CP} = 150A(max)$ , 4V drive	10001-0
CY25BAH-8F	$V_{CES} = 400V(max), I_{CP} = 150A(max), 2.5V drive$	SOP-8

# **Package Dimensions**





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Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001
